

# SOT2084-1

HWFLGA18, thermal enhanced very-very thin fine-pitched land grid array package, 18 terminals, 0.4 mm pitch, 2.4 mm x 2 mm x 0.64 mm body

3 March 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HWFLGA18
<b>Package style descriptive code</b>	LGA (land grid array package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-09-2020
<b>Manufacturer package code</b>	98ASA01669D

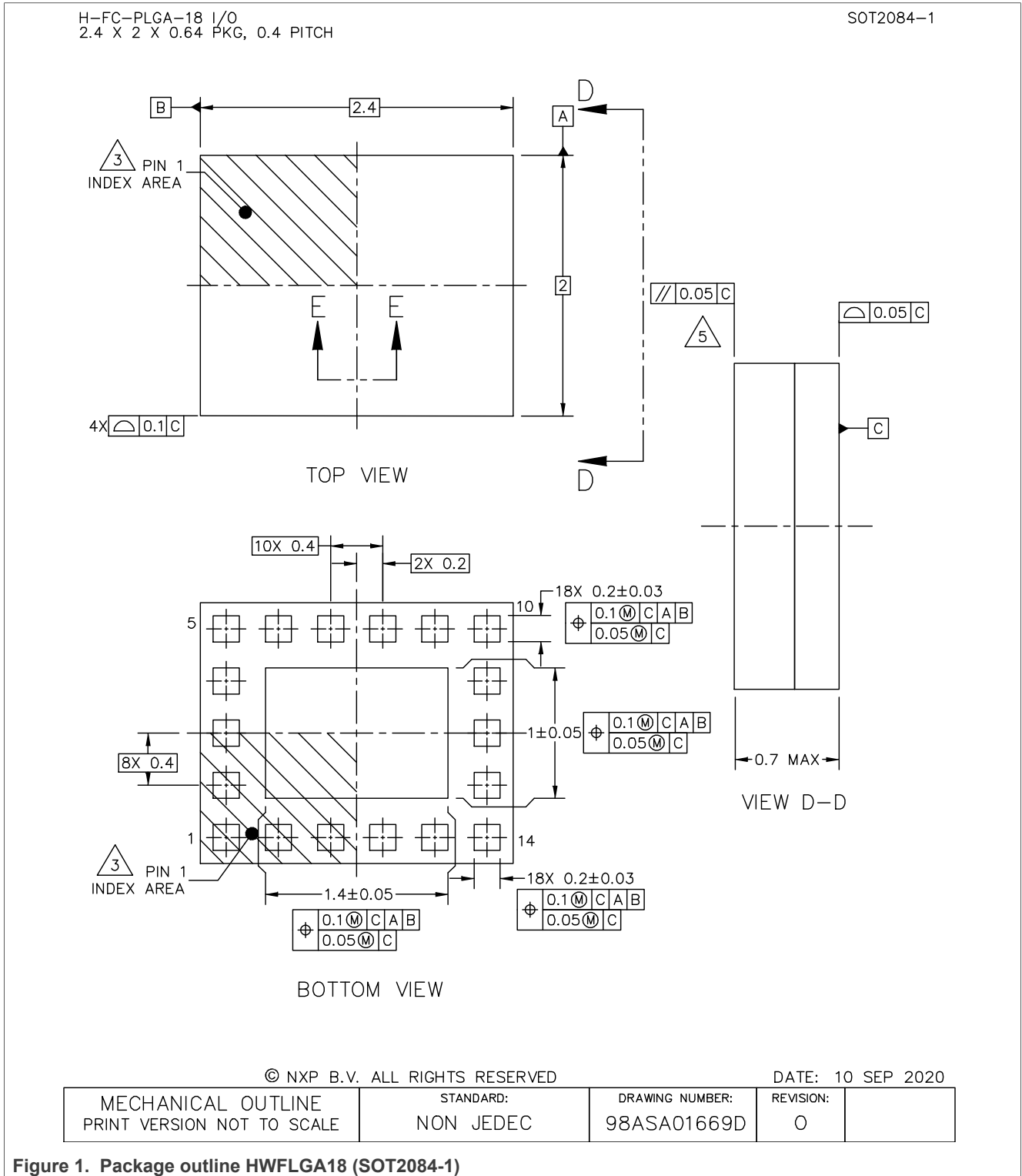
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.3	2.4	2.5	mm
package width	1.9	2	2.1	mm
seated height	-	0.64	0.7	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	18	-	



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2 Package outline



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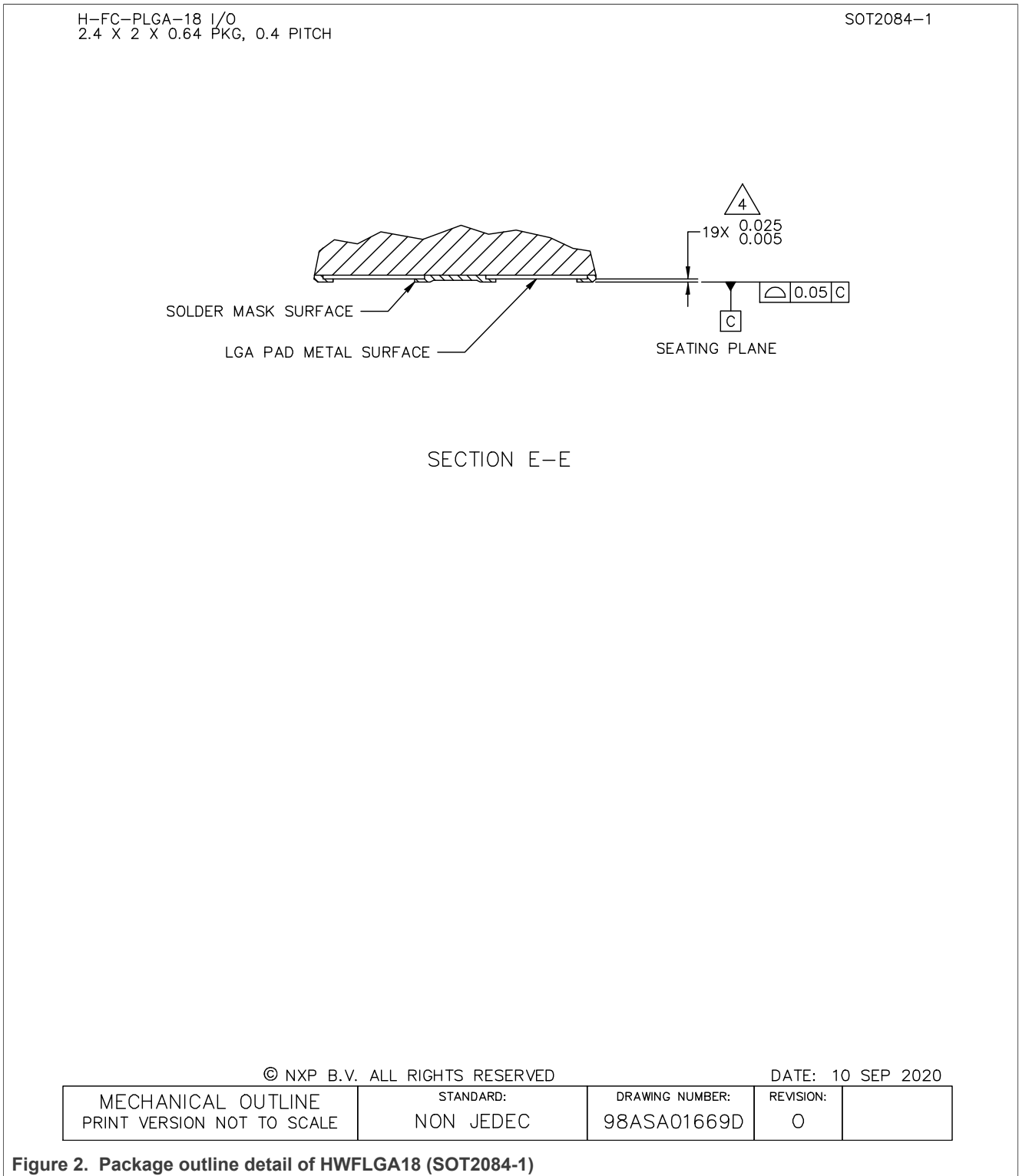
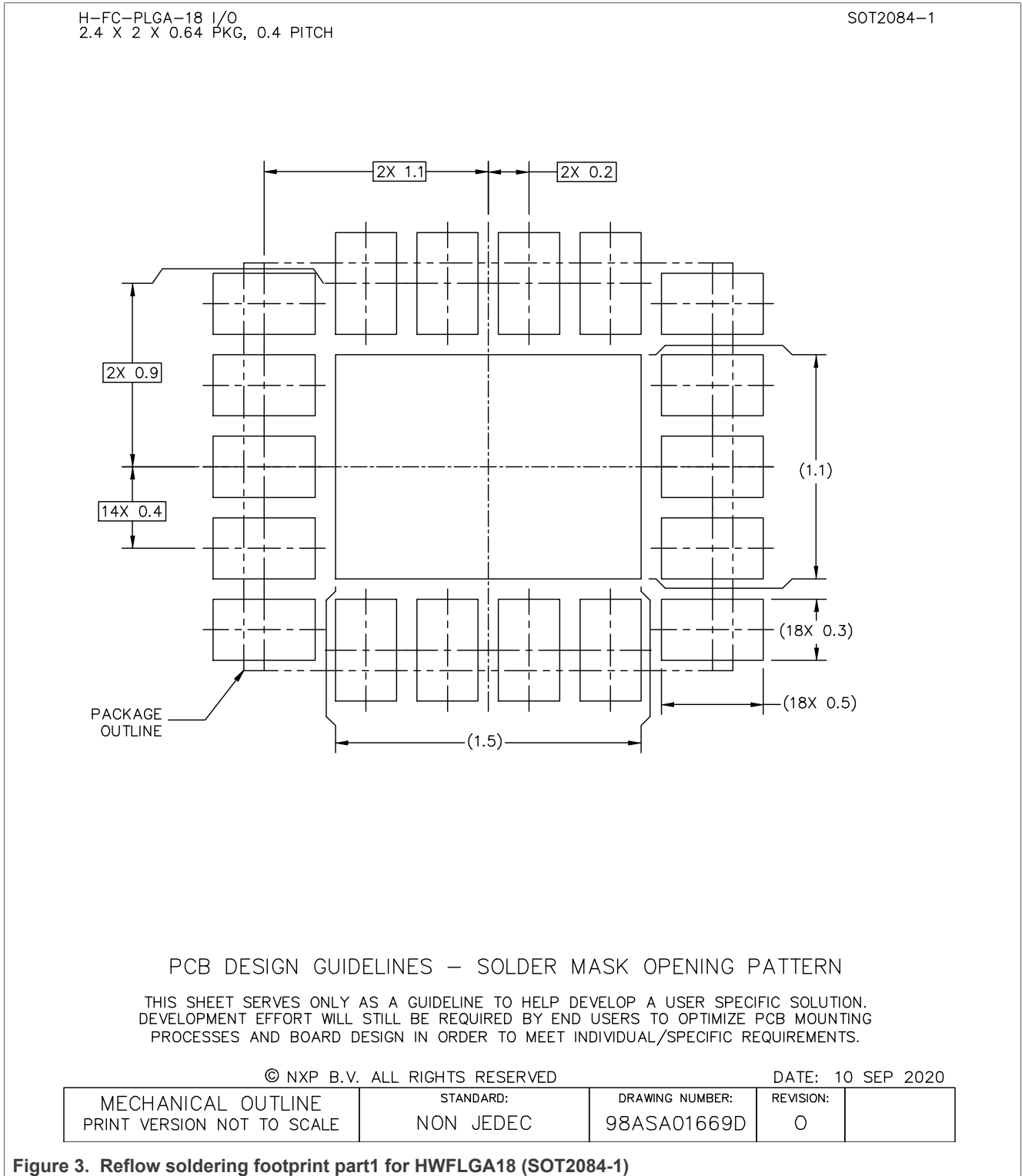


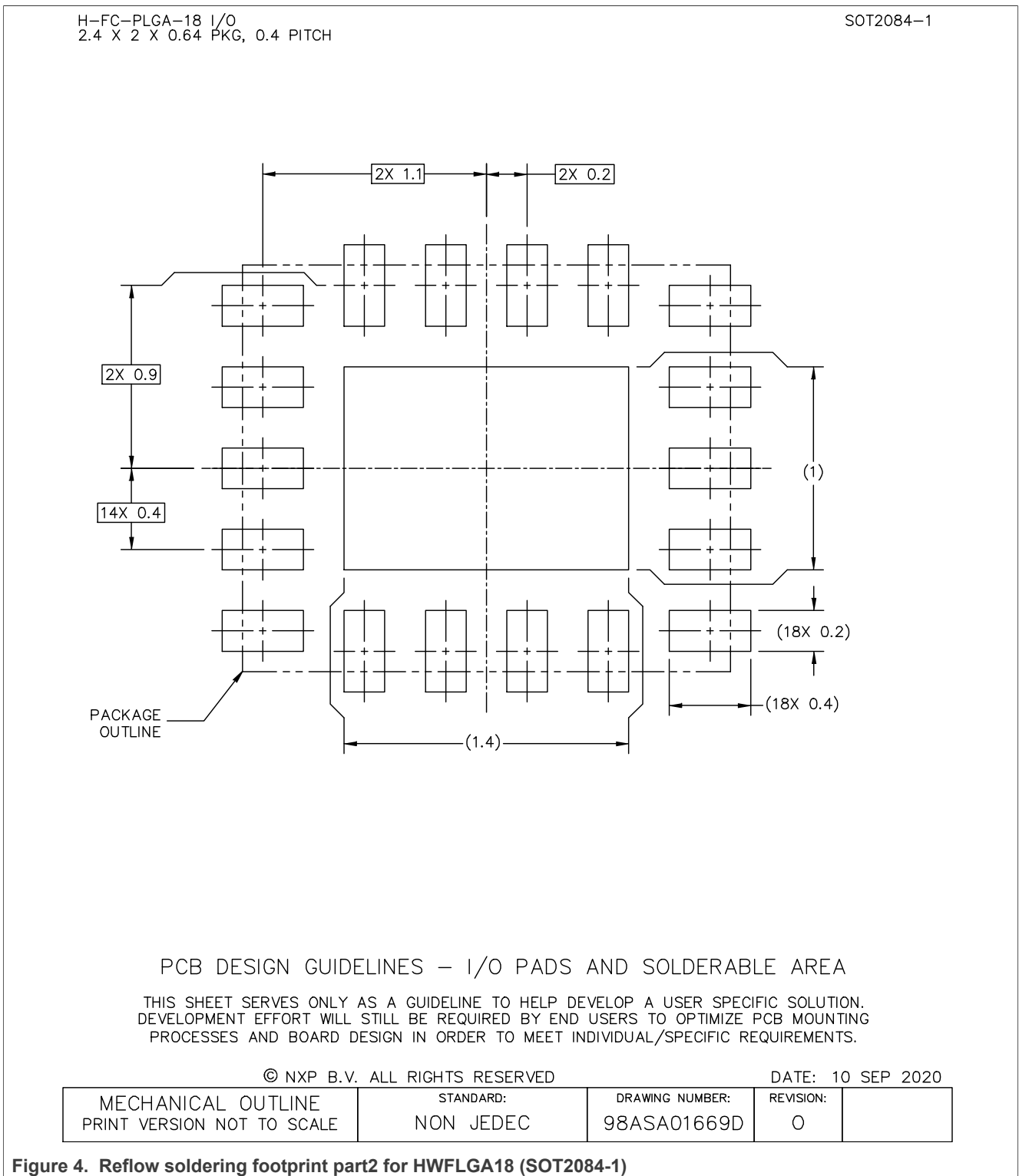
Figure 2. Package outline detail of HWFLGA18 (SOT2084-1)

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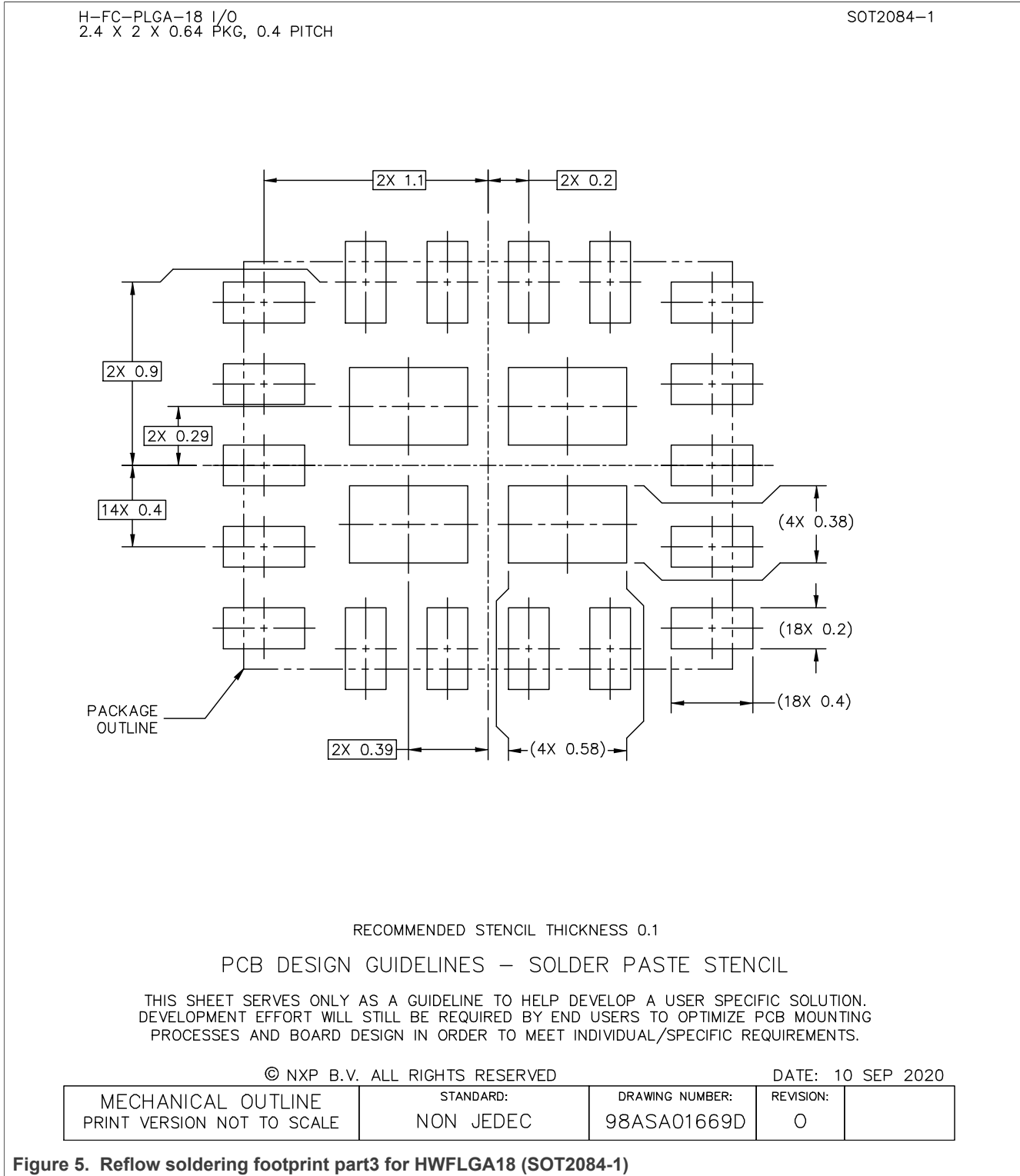
3 Soldering



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H-FC-PLGA-18 I/O  
2.4 X 2 X 0.64 PKG, 0.4 PITCH

SOT2084-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE

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DATE: 10 SEP 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01669D	REVISION: 0	
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**Figure 6. Package outline note HWFLGA18 (SOT2084-1)**

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## 4 Legal information

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